GSE0520Q

Ultra-low Capacitance Bidirectional Micro Packaged TVS Diodes for ESD Protection

Product Description

The GSE0520Q is designed to protect sensitive electronics from damage or latch up due to ESD, lightning, and other voltage induced transient events.

The DFN1006 package type is provided for easy PCB layout.

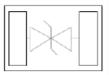
Features

- Max. peak pulse power : PPP=20W at t_P=8/20us
- Stand-off Voltage : 5.0V
- Low capacitance (<0.5pF) for high-speed interfaces
- No insertion loss to 3.0GHz
- Replacement for MLV
- Protects I/O Port
- Low Clamping Voltage
- Low Leakage
- Solid-state Punch-Through TVS Process technology
- IEC61000-4-2(ESD) ±15kV (air), ±8kV (contact)
- Meets MSL 1 Requirements
- RoHS Compliant, 100%Pb & Halogen Free

Applications

- High Speed Line :USB1.0/2.0, VGA, DVI, SDI
- Serial and Parallel Ports
- Notebooks, Desktops, Servers
- Projection TV
- Cellular handsets and accessories
 - Portable instrumentation
- Peripherals

Packages & Pin Assignments



DFN1006

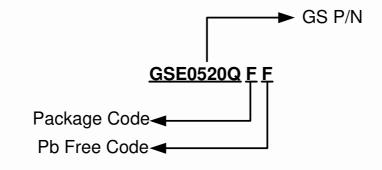
Marking & Orientation



Part Number	Package	Marking
GSE0520QFF	DFN1006	S



Ordering Information



Part Number	Package	Quantity
GSE0520QFF	DFN1006	10000 PCS

Absolute Maximum Ratings (T_A=25°C Unless otherwise noted)

Symbol	Parameter	Typical	Unit
P _{pk}	Peak Pulse Power (t _P =8/20µs)	20	W
	ESD Per IEC61000-4-2 (Air)	±15	kV
V _{PP}	ESD Per IEC61000-4-2 (Contact)	±8	kV
TJ	Operating Junction Temperature Range	-55 to +150	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C
ΤL	Soldering Temperature, t(max)=10s	260	°C

Note : Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Electrical Characteristics

(T_A=25^oC Unless otherwise noted)

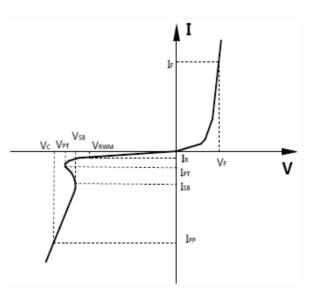
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{RWM}	Reverse Stand-off Voltage	-			5.0	V
V _{BR}	Reverse Breakdown Voltage	I _R =1mA	6.0		10	V
Rdyn	Resistance	-		1.4		Ω
I _R	Reverse Leakage Current	V _{RWM} =5V			1.0	uA
Vc	Clamping Voltage	I _{PP} =1A (8/20µs)			15	V
CJ	Junction Capacitance	V _R =0V,f=1MHz		0.3	0.5	pF

GSE0520Q

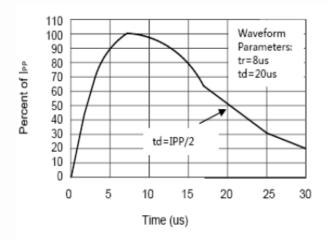


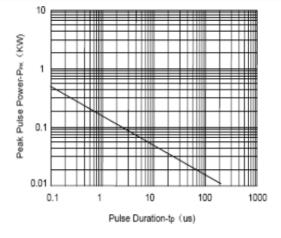
Electrical Parameter

Symbol	Parameter	
Vrwm	Working Peak Reverse Voltage	
Vpt	Punch-Through Voltage@ IpT	
VSB	Snap-Back Voltage@ ISB	
Vc	Clamping Voltage @ IPP	
IT	Test Current	
Irm	Leakage current at VRWM	
Ipp	Peak pulse current	
Co	Off-state Capacitance	
CJ	Junction Capacitance	

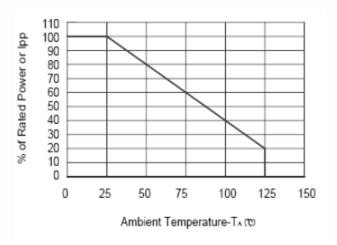


Typical Characteristics





Pulse Waveform



Power Derating Curve

GH

OBA

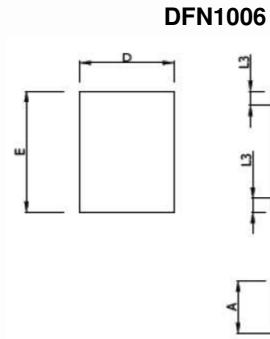
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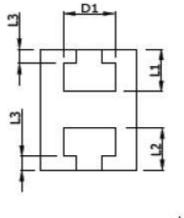
MICONDUCTOR

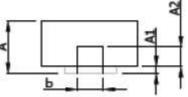
Non-Repetitive Peak Pulse Power vs. Pulse Time



Package Dimension







Dimensions					
Symbol	Millim	eters	Incl	nes	
Symbol	Min	Мах	Min	Max	
Α	0.30	0.40	0.012	0.016	
A1	-	0.05	-	0.002	
A2	0.125 (REF)		0.005 (REF)		
D	0.55	0.65	0.022	0.026	
E	0.95	1.05	0.037	0.041	
D1	0.45	0.55	0.018	0.021	
b	0.15 (REF)		0.006 (REF)		
L1	0.25	0.35	0.010	0.014	
L2	0.25	0.35	0.010	0.014	
L3	0.05 (REF) 0.002 (REF)				



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